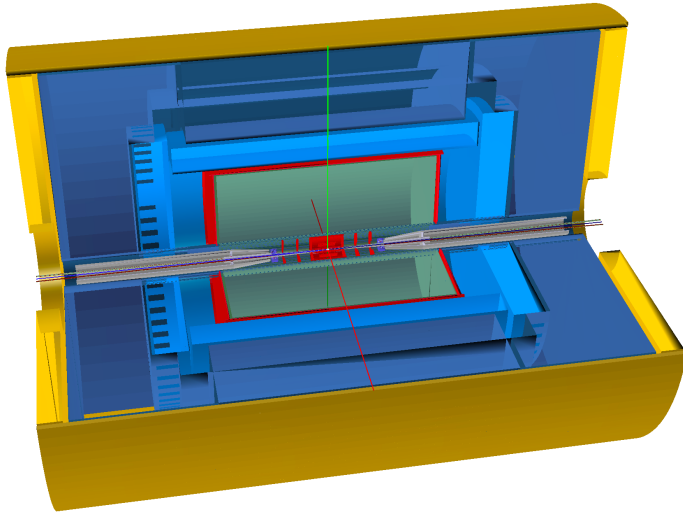


EOI ALLEGRO

Prospectives R&D détecteurs LAPP



Marco Delmastro



31/3/2025

ALLEGRO: a noble liquid calorimeter *and* an FCC detector

Expression of Interest for a Noble Liquid Electromagnetic Calorimeter for the ALLEGRO Detector Concept

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- *ALLEGRO calorimeter R&D in WP2 of DRD6 (which LAPP is officially a member of)*
- *Activity already existing at LAPP since ~2 years*
- *EOI already signed by LAPP members and validated by LAPP Directions*

1 Expression of Interest for the ALLEGRO 2 Full-Detector Concept for FCC-ee

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9 D. Contardo,²¹ M. Corradi,^{11,12} T. Dai,²⁷ M. Dam,²⁸ R. De Asmundis,⁸ A. Deiana,²⁹
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13 D. Fournier,² B. François,¹ J. Fried,³ N. Gallice,³ S. Gao,³ C. Gargiulo,¹ J. Ge,²⁷
14 V. Gkoukousis,²⁴ T. Golling,³⁴ L. Guan,²⁷ Y. Guo,²⁷ G. Haefeli,¹⁹ M. Haviernik,³²
15 C. Herwig,²⁷ M. Himmelsbach,⁹ Z. Huang,² G. Iakovidis,³ P. Iengo,^{7,8} A. Ilg,²⁴
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18 H. Kroha,¹⁵ C. Lange,²⁵ S. Leontsinis,²⁴ T. Li,¹⁷ C. Li,²⁷ T. Loeliger,³⁶ C. Luci,^{11,12}
19 A. Macchiolo,²⁴ A. Maloizel,¹⁷ R. Marchevski,¹⁹ G. Marchiori,¹⁷ J. Maurer,³⁷
20 S. Menke,¹⁵ M. Mentink,¹ O. Mezhenska,³⁸ M. Mlynarikova,¹ S. Mobius,¹⁶ S. Molina,¹
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22 P. Owen,²⁴ F. Palla,^{39,1} T.H. Park,¹⁵ J. Parsons,⁴⁰ R. Pedro,⁴¹ J. Pekkanen,¹ E. Petit,⁴
23 F. Petrucci,¹⁸ I. Polak,⁴² G. Popeneciu,⁴³ G. Proto,¹⁵ J. Qian,²⁷ V. Radeka,³
24 B. Ravina,¹ S. Rescia,³ R. Richter,¹⁵ S. Rosati,¹² J. Rutherford,⁴⁴ E. Salzer,²⁷
25 P. Schacht,¹⁵ S. Schramm,³⁴ T. Schwarz,²⁷ P. Schwemling,⁶ G. Sekhniaidze,⁸
26 S. Senyukov,¹⁰ N. Serra,²⁴ A. Sfyrla,³⁴ L. Shchutska,¹⁹ R. Simonelli,¹ S. Snyder,³
27 O. Solovyanov,⁴⁵ F. Sopkova,³² P. Strizenec,³⁸ G. Suliman,⁴⁶ C. Suslu,²⁷ G. Tarna,³⁷
28 A. Tricoli,³ V. Tudorache,³⁷ A. Upegui,⁴⁷ R. Vari,^{11,12} E. Varnes,⁴⁴ S. Veneziano,^{11,12}
29 A. Verbitskiy,¹⁵ E. Voevodina,¹⁵ R. Wallny,⁵ C. Wang,⁹ C. Weaverdyck,²⁷ M. Weber,¹⁶
30 H. Wilkens,³ Z. Wu,¹³ B. Yu,³ C. Zhang,³ M. Zhao,³ B. Zhou,²⁷ and J. Zhu,²⁷

ALLEGRO: high granularity noble liquid calorimeter for FCC-ee

Baseline design

1536 straight inclined (50.4°) 1.8mm Pb absorber plates_{SEP}

Multi-layer PCBs as readout electrodes_{SEP}

1.2 – 2.4 mm LAr gaps_{SEP}

40 cm deep ($\approx 22 X_0$)_{SEP}

Segmentation:

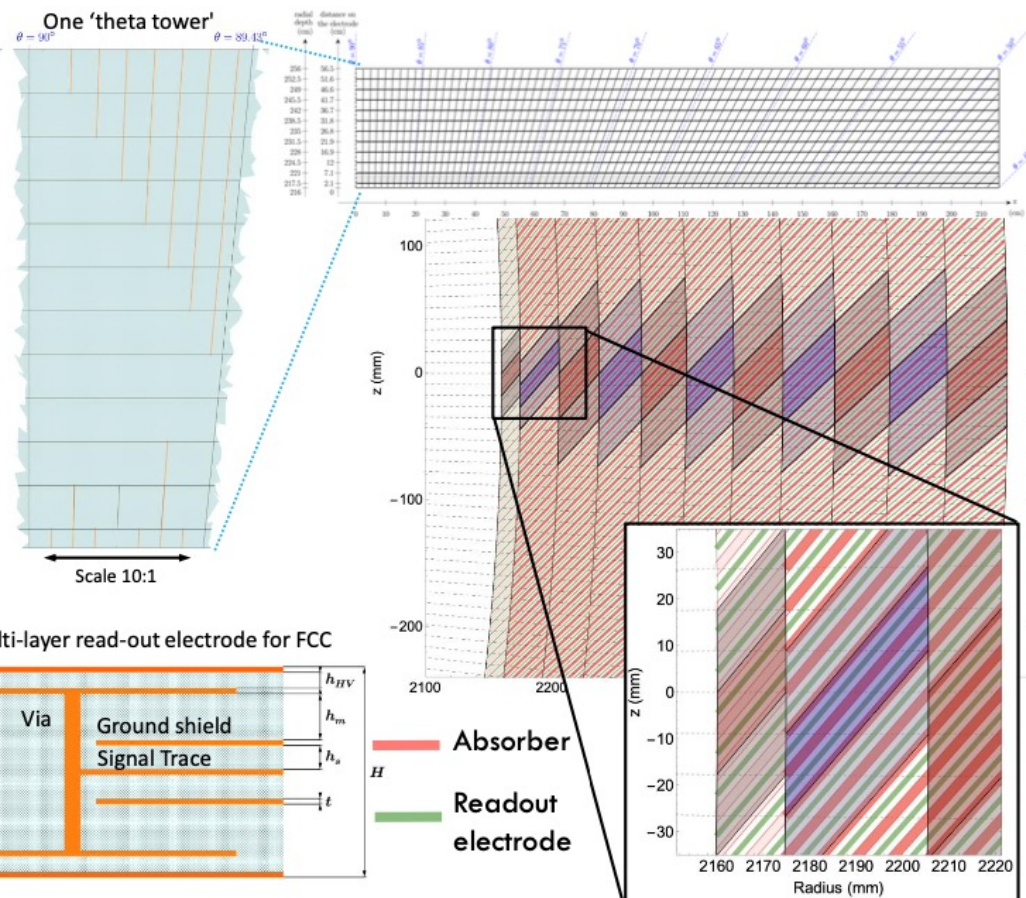
- $\Delta\theta = 10$ (2.5) mrad for regular (1st comp. strip) cells,
- $\Delta\phi = 8$ mrad
- \rightarrow cell size in strips: 5.4mm x 17.8mm x 30mm_{SEP}

12 layers_{SEP}

Implemented in FCC-SW Fullsim

Possible Options

- LKr or LAr, W or Pb absorbers,
- Absorbers with growing thickness
- Granularity optimization
- Al or carbon fiber cryostat
- Warm or cold electronics



ALLEGRO: a full detector concept for FCC-ee



Vertex Detector:

- MAPS or DMAPS possibly with timing layer (LGAD)
- Possibly ALICE 3 like?

Drift Chamber ($\pm 2.5\text{m}$ active)

Silicon Wrapper + ToF:

- MAPS or DMAPS possibly with timing layer (LGAD)

High Granularity ECAL:

- Noble liquid + Pb or W
- Particle Flow reconstruction

Solenoid $B=2\text{T}$, sharing cryostat with ECAL, outside ECAL

- Light solenoid coil $\approx 0.76 X_0$ (see back-up)
- Low-material cryostat $< 0.1 X_0$ (see back-up)

High Granularity HCAL / Iron Yoke:

- Scintillator + Iron (particle flow reconstruction)
 - SiPMs directly on Scintillator or
 - TileCal: WS fibres, SiPMs outside

Muon Tagger:

- Drift chambers, RPC, MicroMegas

ALLEGRO calorimetry: already a (proto) collaboration

- Several IN2P3 institutes, a clear interest at French level
 - ✓ APC, IJCLAB, CPPM, Omega
- CERN
- Various “friendly” institutes we have already collaborated with (e.g. in ATLAS LAr)



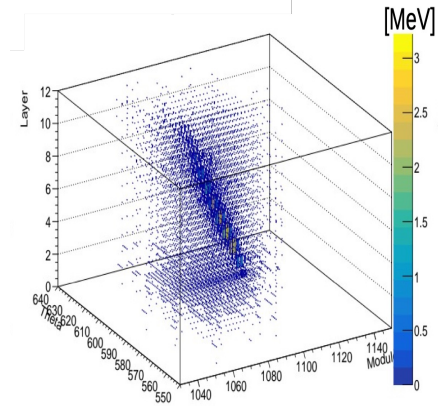
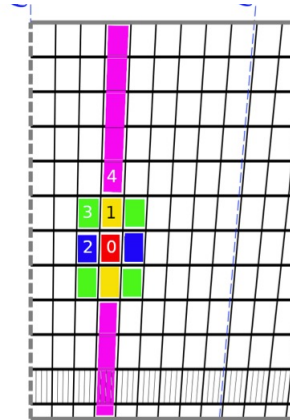
CHARLES
UNIVERSITY



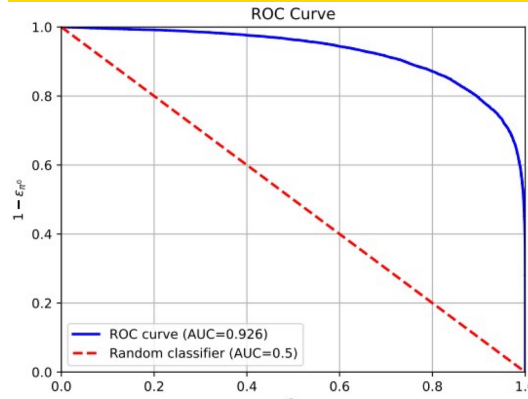
ALLEGRO: what is LAPP already contributing to?

Zhibo

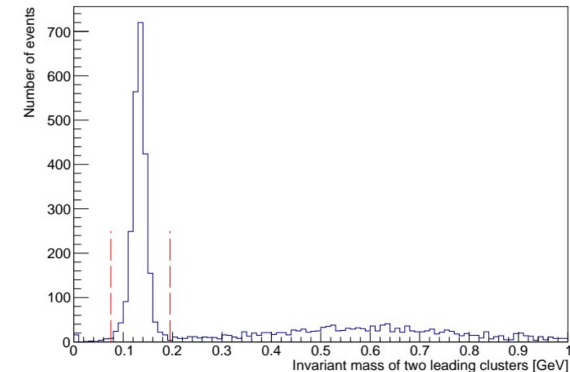
- ALLEGRO calorimeter simulation
 - ✓ Cross-talk and noise simulation in ALLEGRO ECAL
 - ✓ ALLEGRO electrode geometry optimization for optimal reconstruction of electromagnetic showers and particle identification
 - *Talk @ ICHEP 2024: Z. Wu, "R&D studies of the noble liquid calorimeter for ALLEGRO FCC-ee detector concept"*
 - ✓ Pion-photon separation for tau reconstruction (e.g. $Z \rightarrow \tau\tau$ polarization studies)



From cross-talk measurement on electrode prototype at CERN to cross-talk emulation in simulation (LAPP)



Pion/photon separation with ALLEGRO shor shapes



Pion reconstruction from ALLEGRO topoclusters

ALLEGRO ECAL R&D: electrodes

Continue lab tests with small-scale electrode PCB and first large-scale prototype

- Measurements of x-talk and other cell properties
 - Promising to reach $<1\%$ x-talk target
 - Minimize noise aiming for photons down to 300 MeV and $S/N > 5$ for MIPs
- Comparing lab results with Finite Element simulations

Develop endcap design

- Depends on geometry
- Optimize granularity

Finalize barrel design and produce prototype

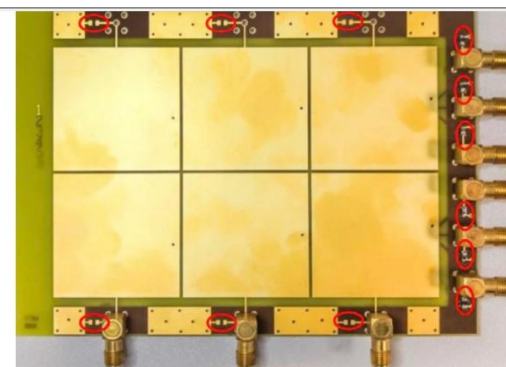
- Readout signals at the back \rightarrow chose connectors

Happening now: excellent opportunity to contribute!

Manufacture test-module electrodes by 2027

- Potentially foresee half of module read-out by cold electronics, other half send signals outside of cryostat with coax

Testbeam opportunity of small-scale prototype in a $O(3)$ years!



Small-scale PCB prototype at IJCLAB



58 cm x 44 cm x 1.2 mm
electrode prototype at CERN

ALLEGRO ECAL R&D: test module

Mechanical design of testbeam module (64 absorbers) has started

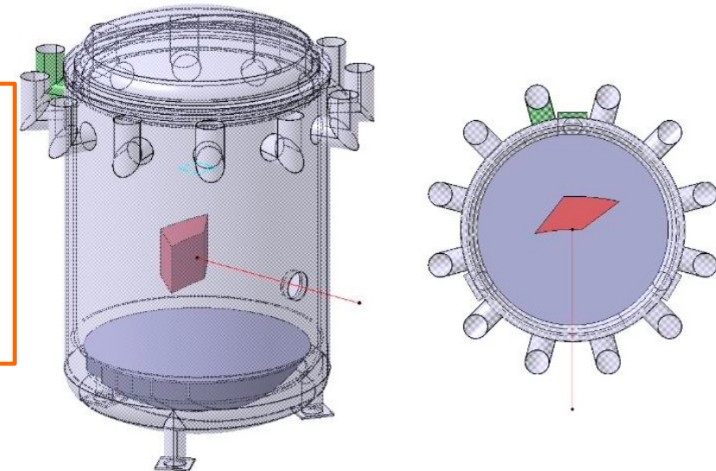
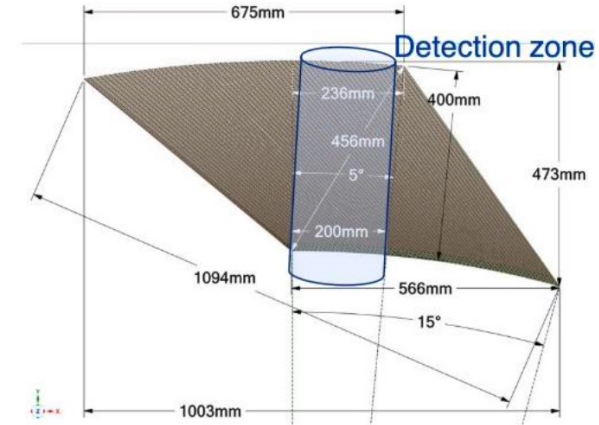
Finite element calculations including

- Rings and G10 bars
- Absorbers and electrodes as shell (2D) elements using layers
- Distance pins
- Six M5 beams join electrodes and absorbers in each side (inner-outer)

Plan to place module into cryostat available at CERN

- But looking into thin carbon-fiber cryostats

Assembly and first tests at warm ~2027, cold tests and test-beam in 2028



- Decrease electrode capacitance (i.e. noise and crosstalk) by geometrical optimization
 - ✓ hatched shielding ground planes
 - ✓ hatched pickup electrode
 - ✓ decrease pickup electrode size with respect to electrode size
- Try other materials to decrease relative permittivity (polyimide ?) → reduce cross talk
- Must perform simulations to check if useful or not
 - ✓ Ansys licences available → do we want to gain expertise ?

*Already in contact
with IJCLAB
colleagues to
mutualize/ learn
simulation expertise*

- Resistive coating may be used to distribute HV on electrodes.
- DLC sputtering allows a wider range and more controlled resistivity, a more robust coating and more controlled thicknesses than historical resistive ink serigraphy.
- Some values commercially available, CERN workshop is able to produce etchable sheets compatible with PCB process.



ALLEGRO ECAL R&D @ LAPP | Push electronic limits?

Renaud

- Technological interest in putting electronic inside the PCB (like a CB)
 - ✓ at least shapers?
 - ✓ lower constraints on crosstalk and on cryostat feedthrough: worth prototyping !

- Use LAPP expertise in flexible printed circuit to design end-of-electrode flex circuit adapter

